

RELIABILITY REPORT  
FOR  
MAX6004EUR+T  
PLASTIC ENCAPSULATED DEVICES

March 30, 2012

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
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Quality Assurance
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## Conclusion

The MAX6004EUR+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX6001-MAX6005 family of SOT23, low-cost series voltage references meets the cost advantage of shunt references and offers the power-saving advantage of series references, which traditionally cost more. Unlike conventional shunt-mode (two-terminal) references that must be biased at the load current and require an external resistor, these devices eliminate the need for an external resistor and offer a supply current that is virtually independent of the supply voltage. These micropower, low-dropout, low-cost devices are ideal for high-volume, cost-sensitive 3V and 5V battery-operated systems with wide variations in supply voltage that require very low power dissipation. Additionally, these devices are internally compensated and do not require an external compensation capacitor, saving valuable board area in space-critical applications.

**II. Manufacturing Information**

A. Description/Function:	Low-Cost, Low-Power, Low-Dropout, SOT23-3 Voltage References
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	October 24, 1998

**III. Packaging Information**

A. Package Type:	3L SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0151 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	N/A
K. Single Layer Theta Jc:	N/A
L. Multi Layer Theta Ja:	336°C/W
M. Multi Layer Theta Jc:	110.1°C/W

**IV. Die Information**

A. Dimensions:	44 X 31 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)  
Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 130 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 8.4 \times 10^{-9}$$

$$\lambda = 8.4 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.06 @ 25C and 1.06 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (lot NQ9CAN001C D/C 9833)

The RF23-8 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX6004EUR+T**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters	50	0	SQ9AEQ003A, D/C 0424
	Biased	& functionality	80	0	SQ9EEY006BI, D/C 0409
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.